

SOT727-1

plastic thermal enhanced low profile ball grid array package;
475 balls; body 35 x 35 x 0.9 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLBGA475
Package type industry code	HLBGA475
Package style descriptive code	HLBGA (thermal enhanced low profile ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-192
Mounting method type	S (surface mount)
Issue date	7-2-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		34.8	-	35	35.2	mm
E	package width		34.8	-	35	35.2	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		0.8	-	0.9	1	mm
n ₂	actual quantity of termination		-	-	475	-	



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2. Package outline

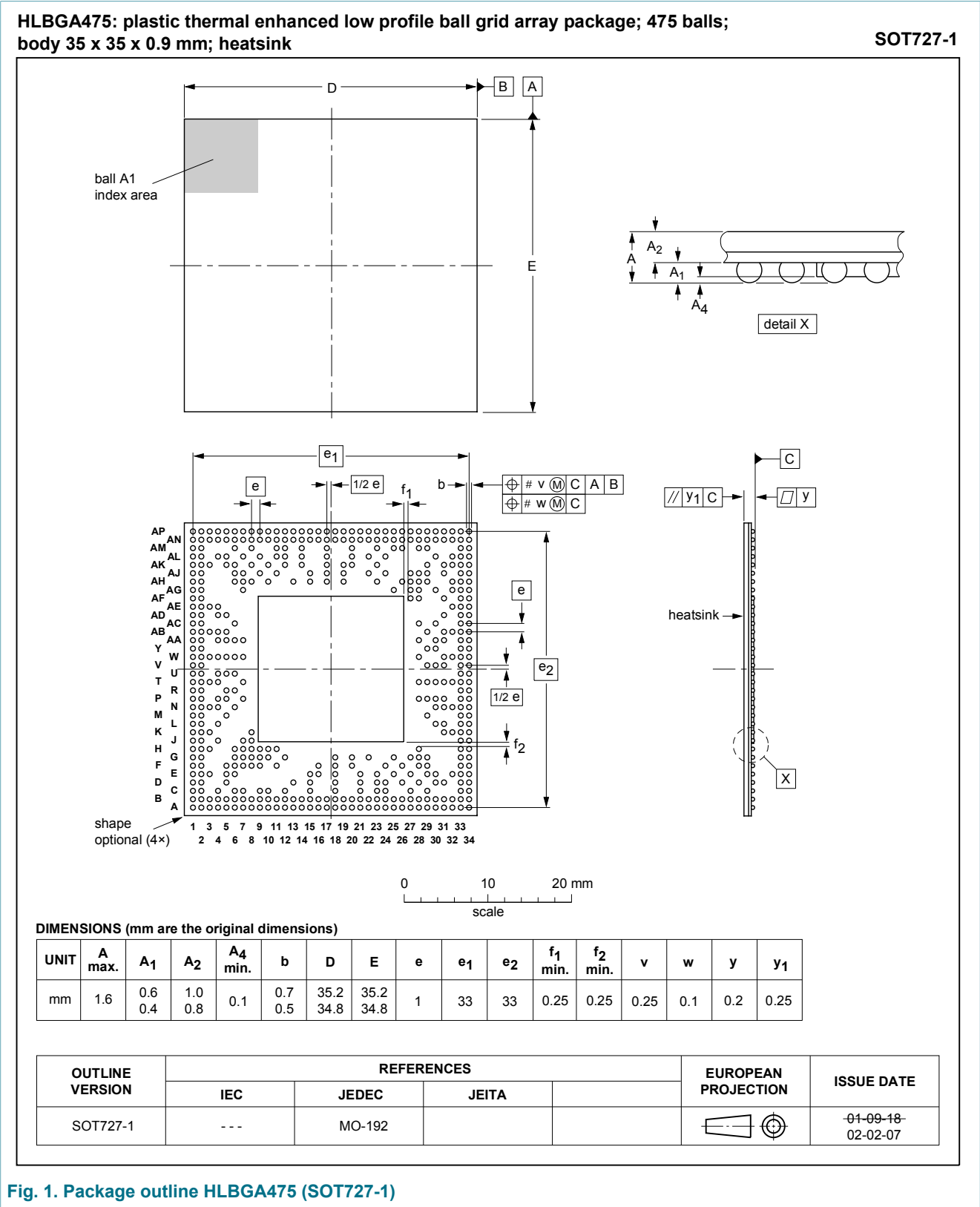


Fig. 1. Package outline HLBGA475 (SOT727-1)

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3. Soldering

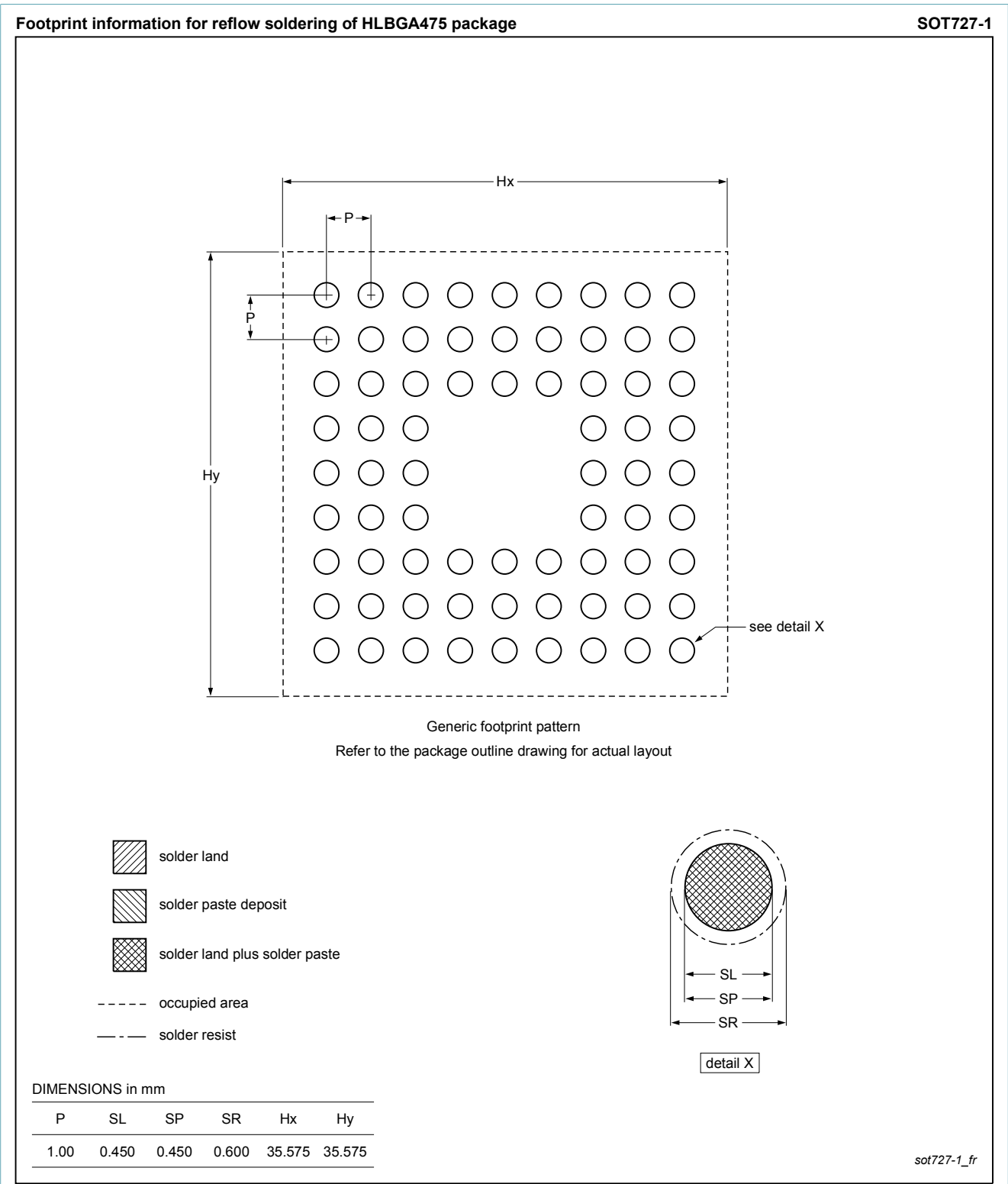


Fig. 2. Reflow soldering footprint for HLBGA475 (SOT727-1)

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4. Legal information

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